



Advanced Fabric Innovations to Maximize the Performance of HPEC Systems

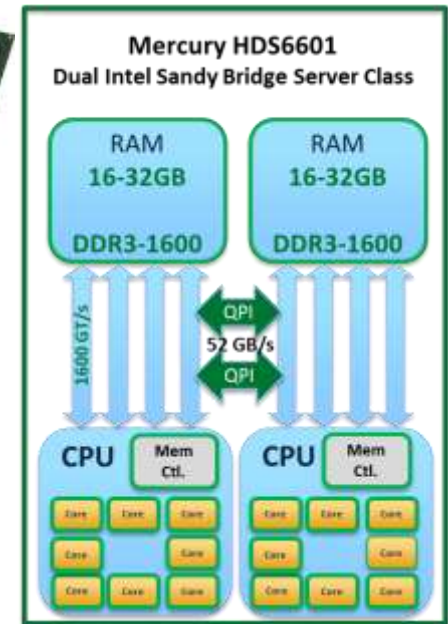
Marc Couture
Director, Product Management

Arnold Sodder
Consulting Systems Architect

Embedded Technology Trends
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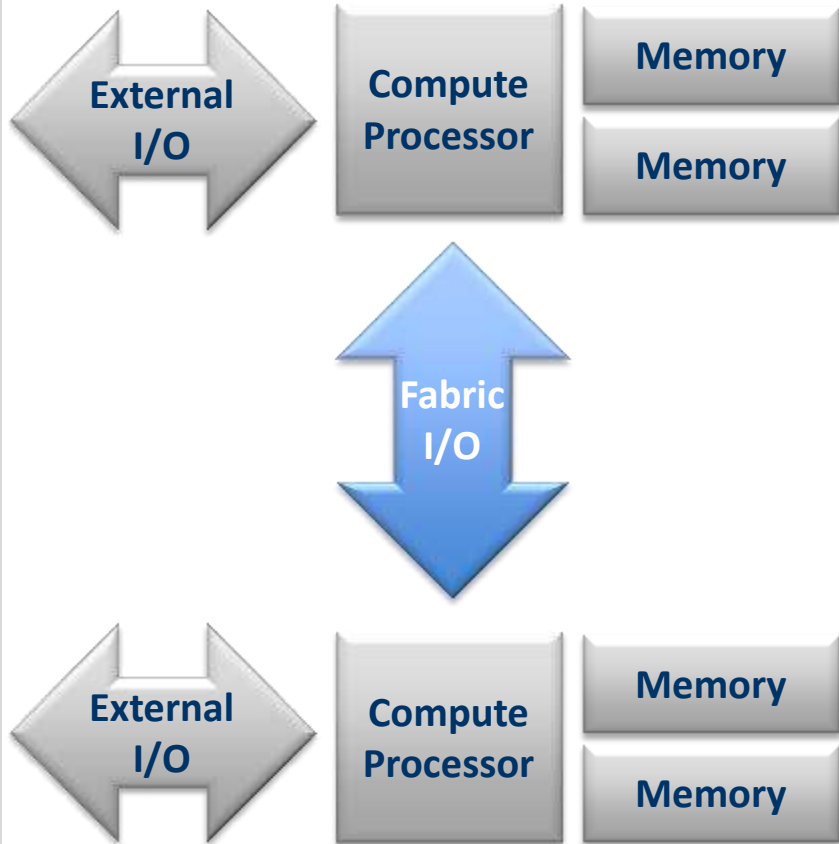
Processing Density shows no sign of stopping

- AVX Core count, Shader Processor count, going up as nm geometry goes down
- Intel
 - Mobile Class has four AVX/AVX2-enabled cores + GT2/3 GPUs
 - Server Class moving from 8 cores to 10 and even 12 per device
- GPUs
 - AMD
 - 960 processors in 40nm 6970M
 - 1280 processors in 28nm 7970M
- Two of the above devices, Intel or GPU, can fit onto a single 6U OpenVPX module for an immense amount of compute power



Hard to become compute bound, but I/O bound is easy

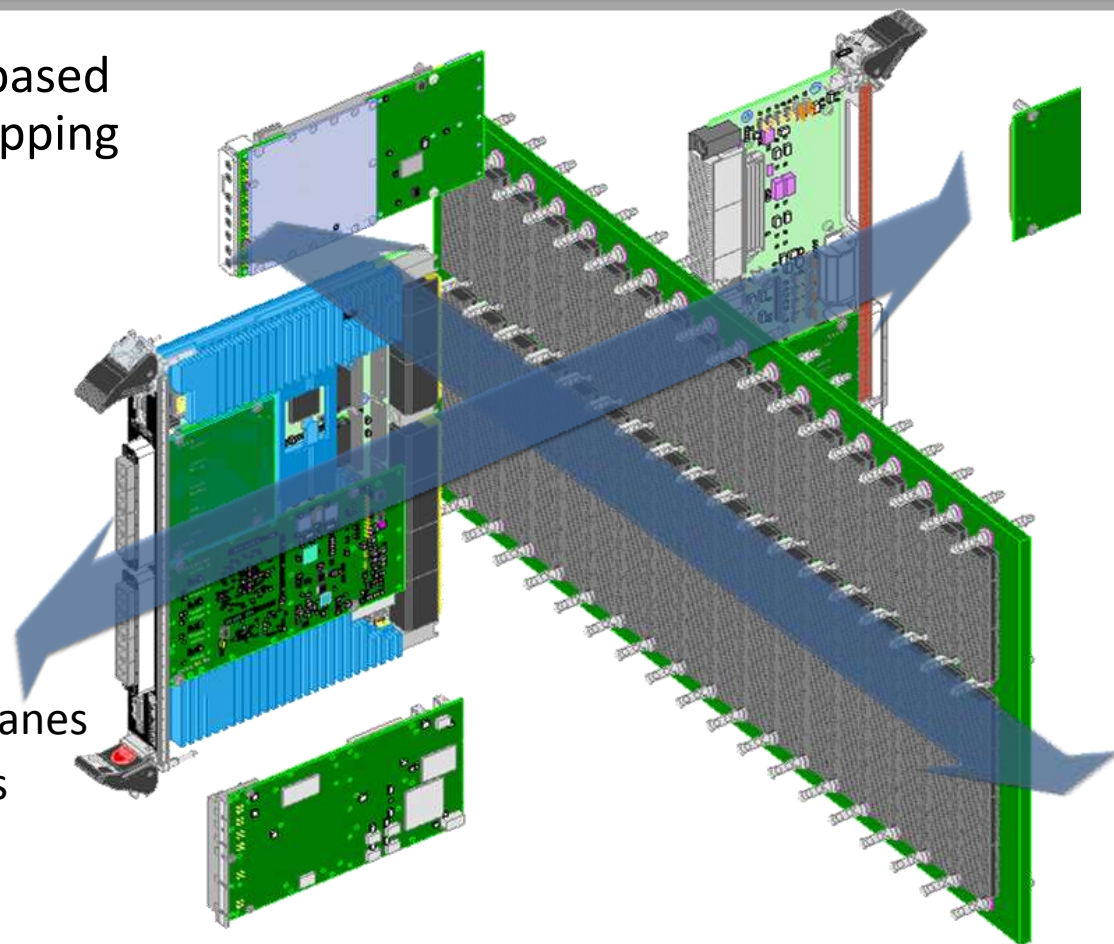
Maximizing Capability per SWaP-C Platform



Balancing Compute, Memory, I/O (External & **Fabric**) Bandwidth

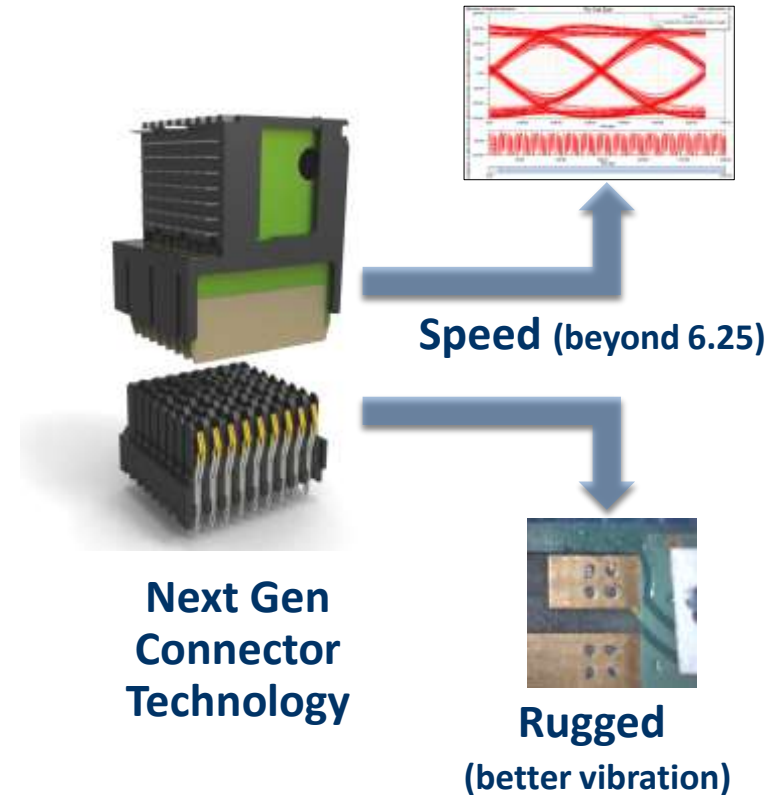
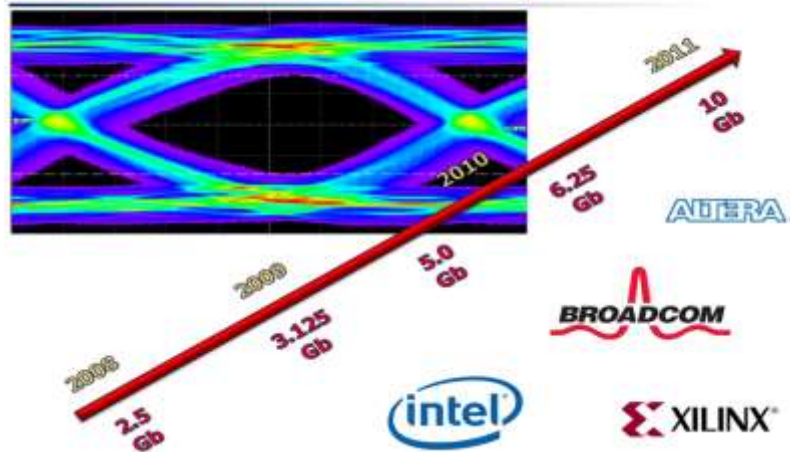
Advances in Backplane Technology Needed for Next-Gen Interconnects

- Current OpenVPX backplane based on standard RT2 connector topping out at 6.25 Gbaud due to increasing:
 - Channel Loss
 - Channel Reflection
 - Channel Cross Talk
- Signal Integrity loss becomes exaggerated with increasing:
 - Slot count
 - Dataplane & Expansion Plane lanes
 - Traffic on mezzanine and RTMs
 - Temperature extremes
 - Vibration



We need to speed up without degradation

Next Generation Infrastructure



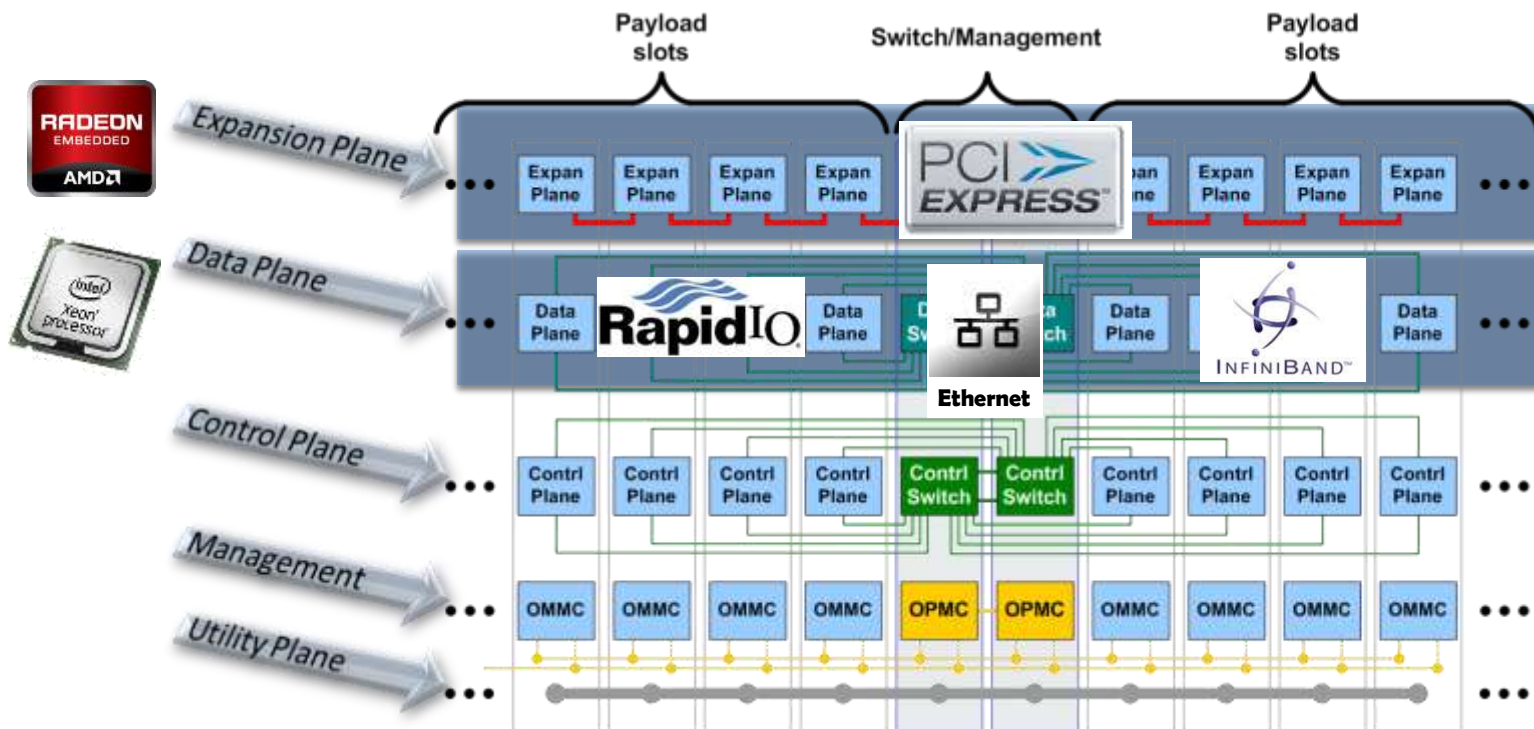
- Advances in connector and backplane technology will get us to 8.0 Gbaud and beyond, needed for Next-Gen Fabric Interconnects:
 - PCIe Gen 3
 - Infiniband QDR
 - 40 GigE

The connector is the key to unlocking speed!

The OpenVPX Multi-Plane Elevation

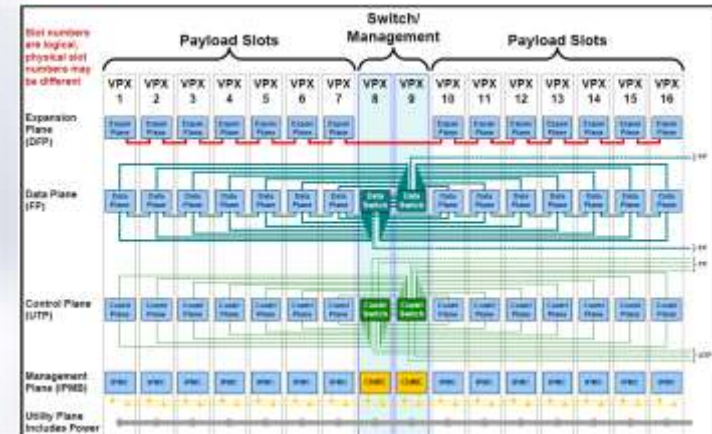
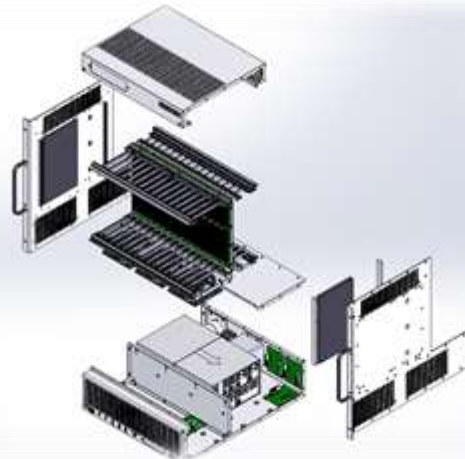
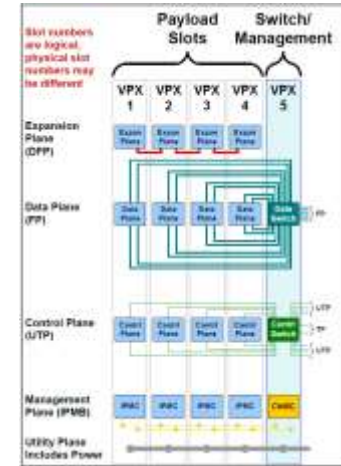
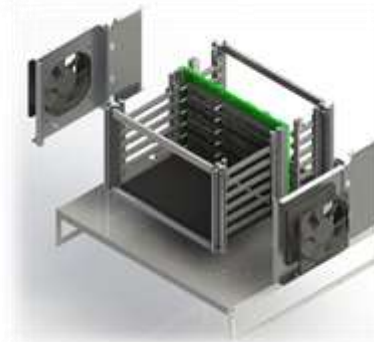
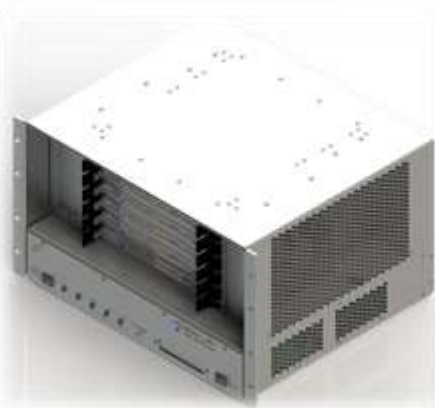


- Choices for the Data Plane mesh/switch fabric are varied
- The Expansion Plane is primarily PCIe



Enabling sophisticated interactions within the system

Example Topologies, Switched Dataplane

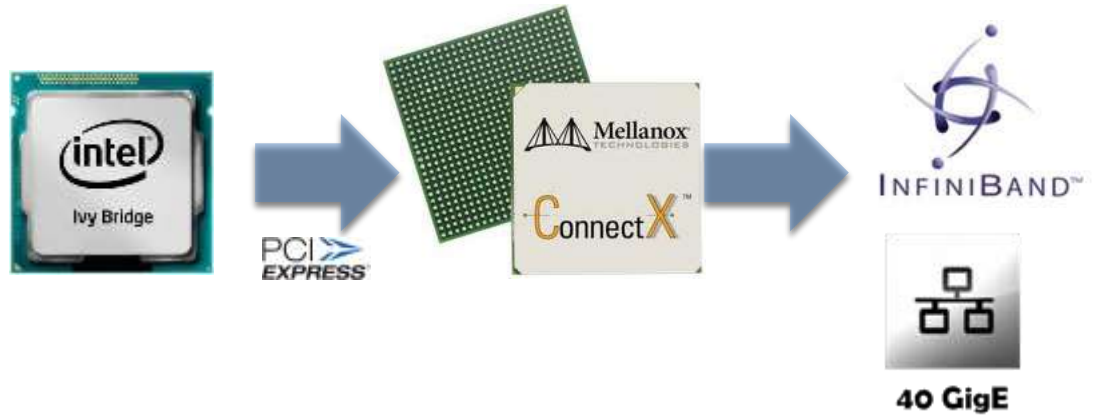
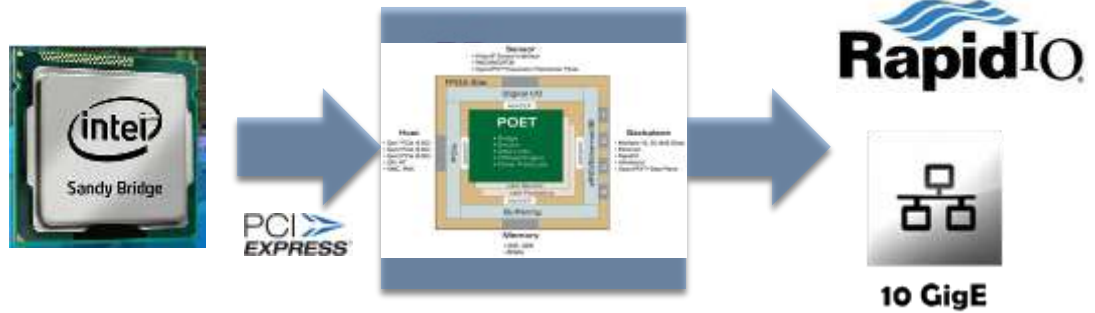


Matching the problem with slots that scale effectively

Payload Fabric Endpoints



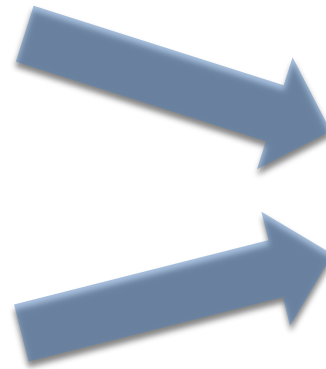
- Currently utilizing Protocol Offload Engine Technology (POET™) IP on FPGAs for Serial RapidIO Gen 2 @ 3.125, 5.0, and 6.25 Gbaud/sec and 10 GigE
- Will be using Mellanox ConnectX-3 for InfiniBand at various rates and eventually 40 GigE
- Will intersect back with POET IP on FPGAs in the future



Next, we need to speed up the I/O to the processors

Intel Server Class coupled with Mellanox

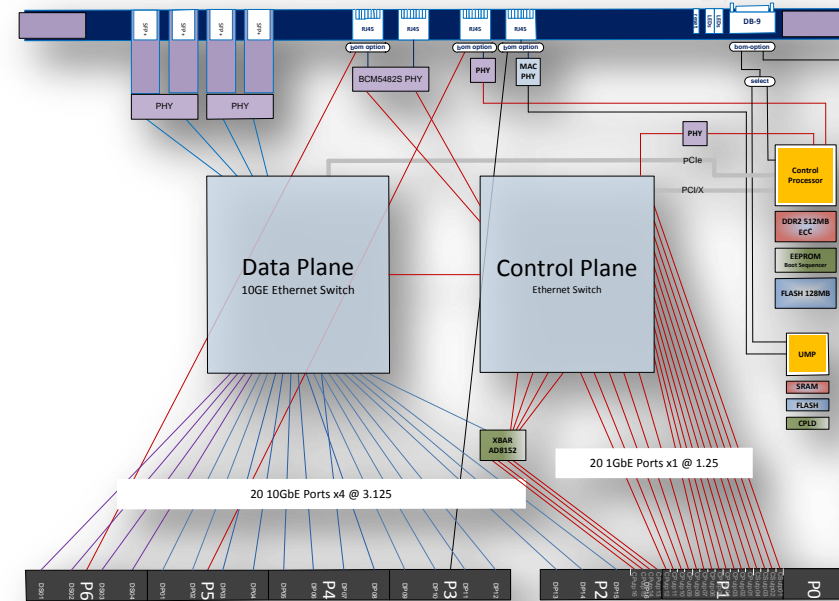
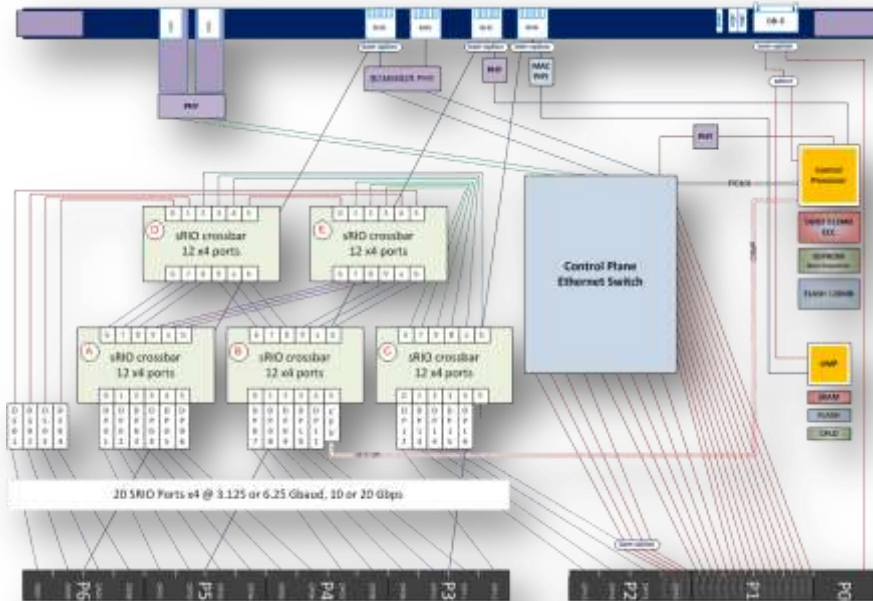
- Addresses the InfiniBand HPC market (e.g. Bladecenter) providing a path to embedded 6U OpenVPX
- Utilizes Mellanox ConnectX-3 for InfiniBand DDR, QDR
- Supports OFED, tightly coupled to InfiniBand
- Same analogy for 40GigE



Mobilization/Ruggedization of the Server

OpenVPX Switch Modules for HPEC

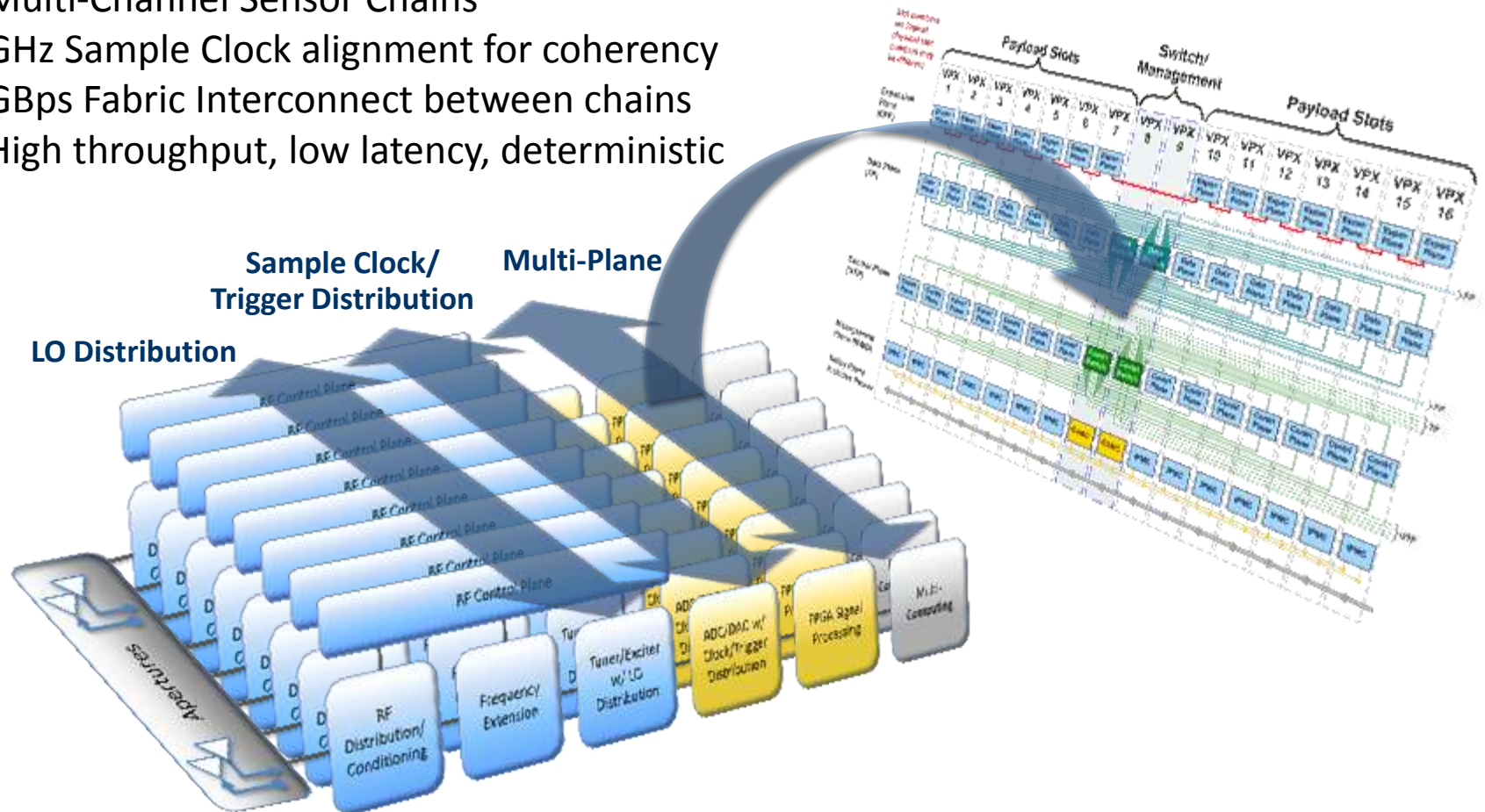
Dedicated Fabric Switches become increasingly important with increased slot-count, providing location-independent processing



SRIO & 10GigE today, Moving to InfiniBand and 40GigE tomorrow

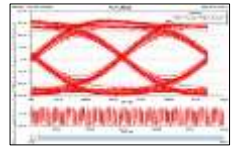
Fabric Interconnect Enabling Multi-Dimensional Apps

- Multi-Channel Sensor Chains
- GHz Sample Clock alignment for coherency
- GBps Fabric Interconnect between chains
- High throughput, low latency, deterministic



Sensor I/O Integrated into the Switched Fabric

HPEC Fabric Key Points



- The current VPX infrastructure is stalling out from an Signal Integrity aspect
- Next gen connector, backplane, and cooling technologies will kick OpenVPX into the next gear
- We'll be able to get maximum mileage out of these massive many-core HPEC compute engines
- And we'll be able to put them in tight spots (SWaP)

Breaking through to the next level with HPEC in OpenVPX



Q & A

Thank You